/ Revised record

A	2022-8-9	all			

/ Descriptions

SOD-323
Schottky Diode in a SOD-323 Plastic Package.

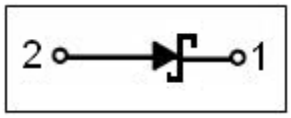
/ Features

Schottky diodes,HF Product.

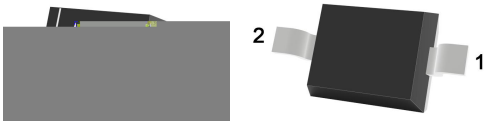
/ Applications

.
Small signal diode.

/ Equivalent Circuit



/ Pinning



PIN1:Cathode PIN2:Anode

/ Marking

Marking	H86

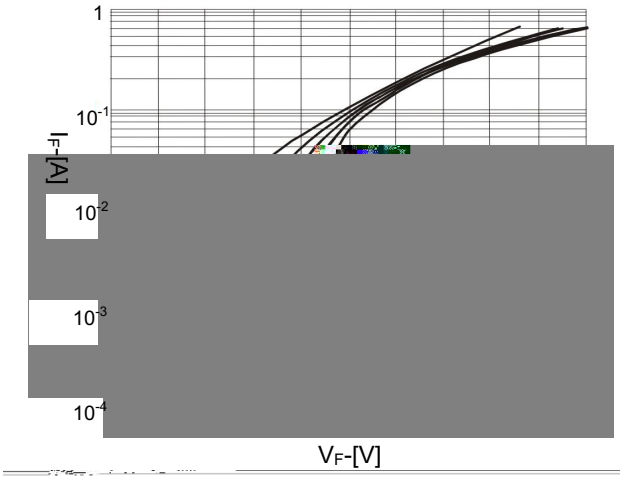
/ Absolute Maximum Ratings(Ta=25)

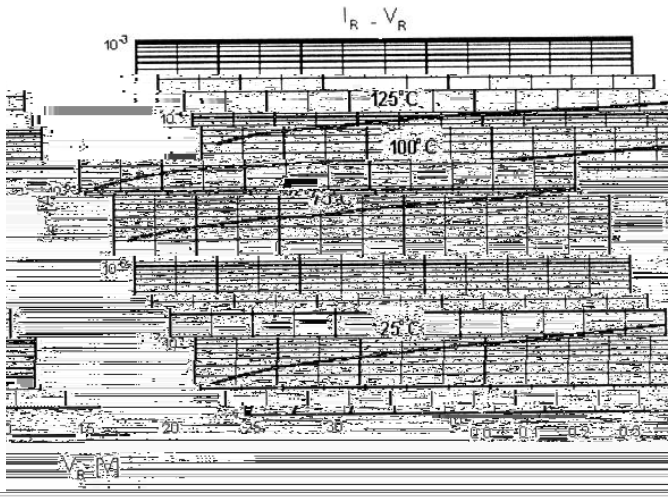
Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Continuous forward current	I_F	200	mA
Surge non repetitive forward current	I_{FSM}	600	mA
Power Dissipation	P_D	250	mW
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	430	℃/W
Junction Temperature Range	T_J	150	℃
Storage Temperature Range	T_{stg}	-55～150	℃

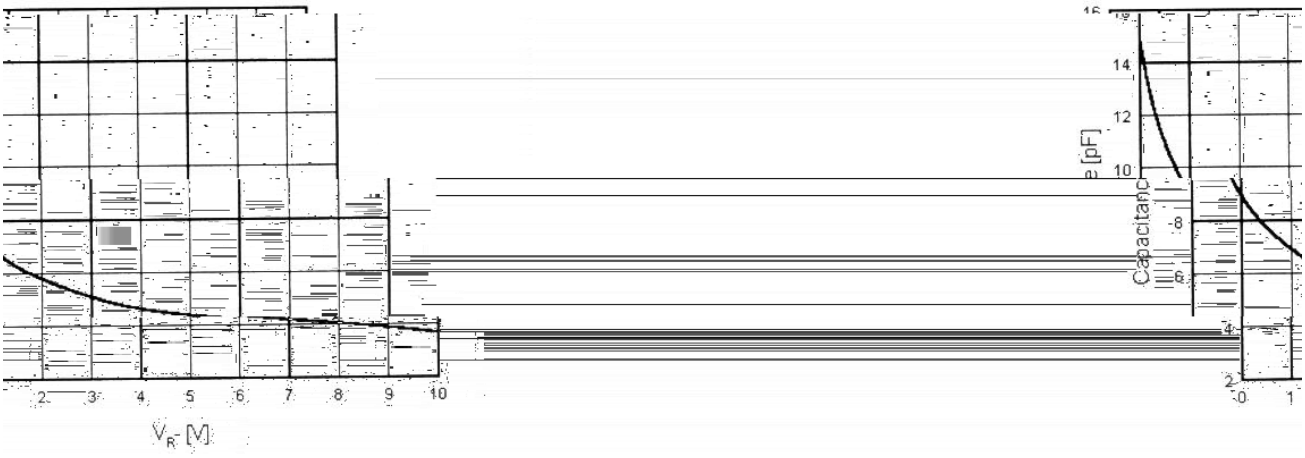
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Rating		Unit
			MIN	MAX	
Reverse Voltage	V_R	I_R=10μA	30		V
Peak Forward voltage	V_F	I_F=0.1mA		240	mV
		I_F=1.0mA		320	mV
		I_F=10mA		400	mV
		I_F=30mA		500	mV
		I_F=100mA		0.8	V
Instantaneous Reverse Current	I_R	V_R=25V		2.0	μA
Total capacitance	C_T	V_R=1.0V f=1.0MHz		10	pF
Reverse recovery time	t_{rr}	I_{RR}=1.0mA R_L=100Ω I_F=1_R=10mA		5.0	ns

/ Electrical Characteristic Curve

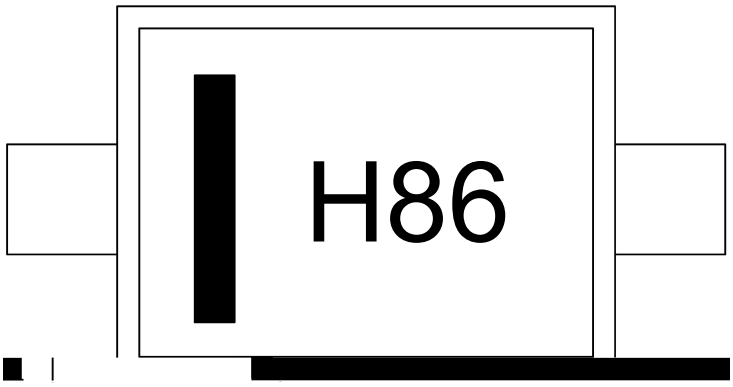






BAT54WS
Rev.A Aug.-2022

/ Marking Instructions



说明：

H： 为公司代码

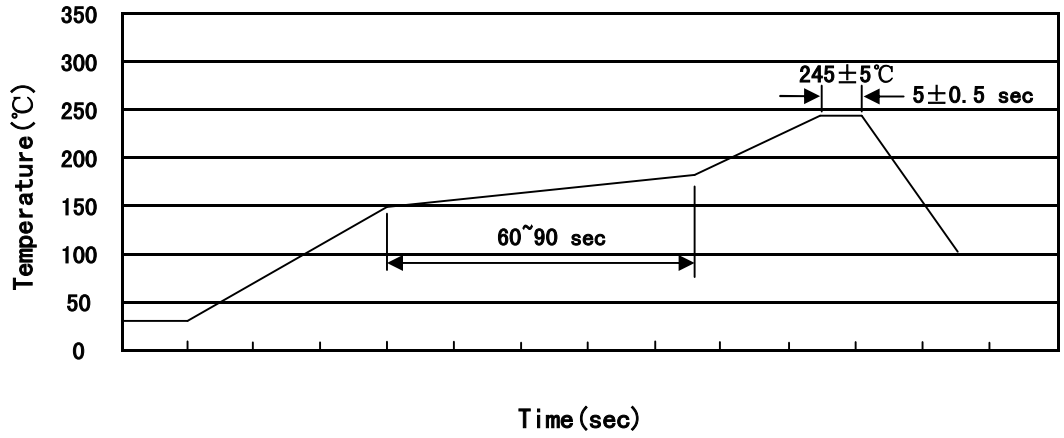
86： 为型号代码

Note:

H: Company Code

86: Product Type

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



						Note:
1		150	180	60	90sec;	1.Preheating:150~180℃, Time:60~90sec.
2		245±5			5±0.5sec;	2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3			2	10℃/sec.		3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

260±5℃	10±1 sec.	Temp.:260±5℃	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm^3)
	只卷盘	卷盘盒	只盒	盒箱	只箱			
						〃		

/ Notices